

General Description

The MIC4467/8/9 family of 4-output CMOS buffer/drivers is an expansion from the earlier single- and dual-output drivers, to which they are functionally closely related. Because package pin count permitted it, each driver has been equipped with a 2-input logic gate for added flexibility. Placing four high-power drivers in a single package also improves system reliability and reduces total system cost. In some applications, one of these drivers can replace not only two packages of single-input drivers, but some of the associated logic as well.

Although primarily intended for driving power MOSFETs, and similar highly capacitive loads, these drivers are equally well suited to driving any other load (capacitive, resistive, or inductive), which requires a high-efficiency, low-impedance driver capable of high peak currents, rail-to-rail voltage swings, and fast switching times. For example, heavily loaded clock lines, coaxial cables, and piezoelectric transducers can all be

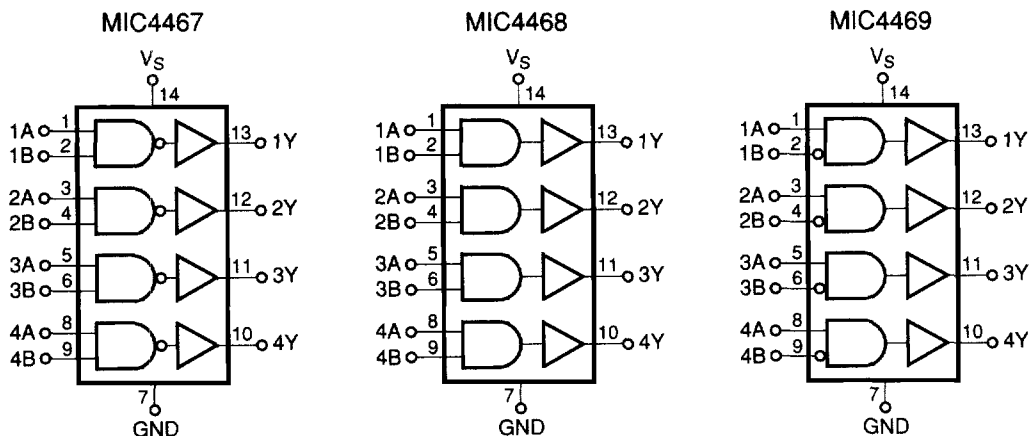
Features

- Built using reliable, low power CMOS processes
- Latchproof. Withstands 500mA Inductive Kickback
- 3 Input Logic Choices
- Symmetrical Rise and Fall Times 25ns
- Short, Equal Delay Times 75ns
- High Peak Output Current 1.2A
- Wide Operating Range 4.5 to 18V
- Low Equivalent Input Capacitance (typ) 6pF
- Inputs = Logic 1 for Any Input From 2.4V to V_S
- ESD Protected

Applications

- General-Purpose CMOS Logic Buffer
- Driving All 4 MOSFETs in an H-Bridge
- Direct Small-Motor Driver
- Relay or Peripheral Drivers
- Dual Differential Output Power Drivers
- CCD Driver
- Pin-Switching Network Driver

Logic Diagrams



driven easily with MIC446X series drivers. The only limitation on loading is that total power dissipation in the IC must be kept within the power dissipation limits of the package.

The MIC446X series drivers are built using a BCD process. They will not latch under any conditions within their power and

voltage ratings. They are not subject to damage when up to 5V of noise spiking (either polarity) occurs on the ground line. They can accept up to half an amp of inductive kickback current (either polarity) into their outputs without damage or logic upset.

Ordering Information

Part No.	Package	Temp. Range
MIC44xxCN*	14-Pin Plastic DIP	0° to +70°C
MIC44xxCWM*	16-Pin Wide SOIC	0° to +70°C
MIC44xxBN*	14-Pin Plastic DIP	-40° to +85°C
MIC44xxBWM*	16-Pin Wide SOIC	-40° to +85°C
MIC44xxAJ*	14-Pin CerDIP	-55° to +125°C
SMD see below	14-Pin CerDIP	-55° to +125°C
MIC44xxAL*	20-Pin LCC	-55° to +125°C

Truth Table

Part No.	Inputs		Output Y
	A	B	
MIC4467 (Each Driver)	L	X	H
	X	L	H
	H	H	L
MIC4468 (Each Driver)	H	H	H
	L	X	L
	X	L	L
MIC4469 (Each Driver)	L	X	L
	X	H	L
	H	L	H

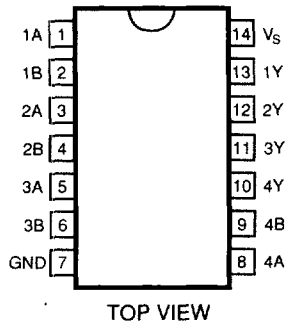
* xx identifies input logic:
67 — NAND

68 — AND
69 — AND with one inverting input

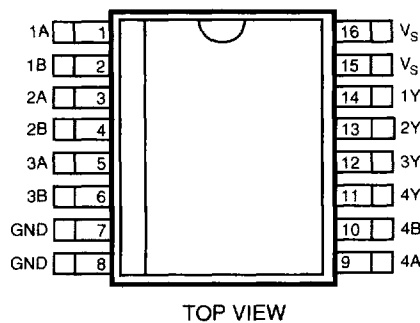
SMD number 5962-9459401MCA for MIC4467AJBQ
SMD number 5962-9459402MCA for MIC4468AJBQ
SMD number 5962-9459403MCA for MIC4469AJBQ

Pin Configurations

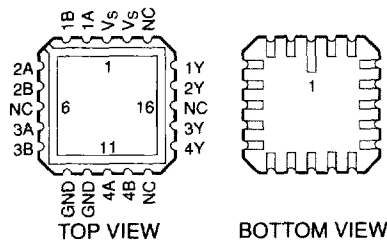
14-Pin Dual-In-Line Package - N, J



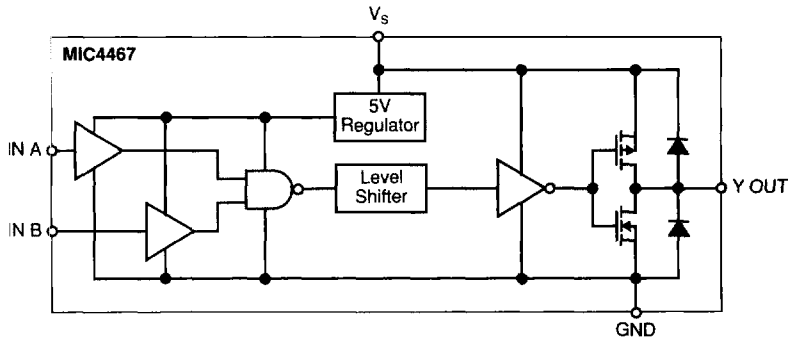
16-Pin Wide SOIC - WM



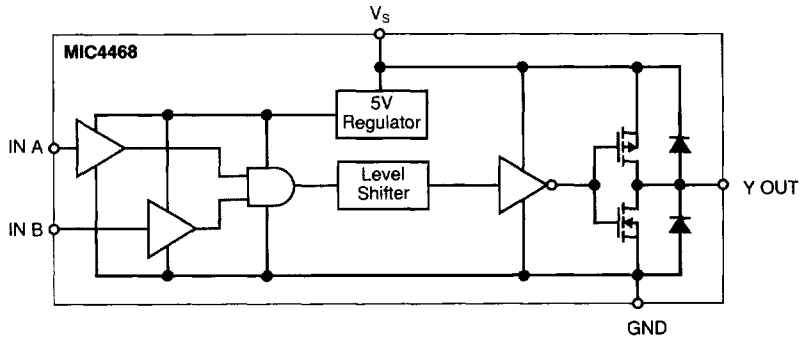
20-Pin LCC - L



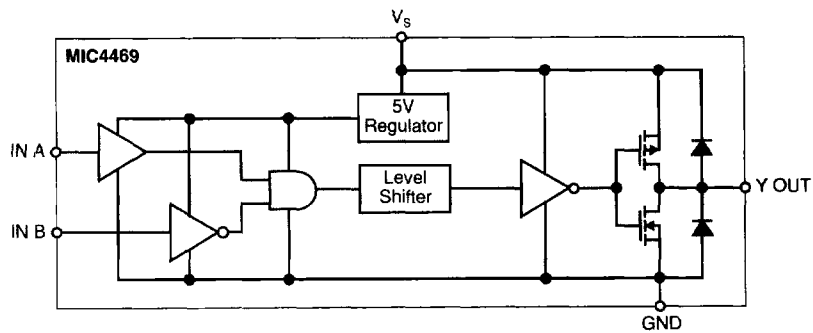
Block Diagrams



Functional Diagram for One Driver (Four Drivers per Package—Ground Unused Inputs)



Functional Diagram for One Driver (Four Drivers per Package—Ground Unused Inputs)



Functional Diagram for One Driver (Four Drivers per Package—Ground Unused Inputs)

Absolute Maximum Ratings (Notes 1 and 2)

Supply Voltage	22V	Power Dissipation	
Input Voltage (GND – 5V) to (V _S + 0.3V)		P Package (14-Pin Plastic DIP)	1.5W
Maximum Chip Temperature		WM Package (16-Pin Wide SOIC)	1W
Operating	150°C	J Package (14-Pin CerDIP)	1.25W
Storage	–65° to +150°C	L Package (20-Pin LCC)	1W
Maximum Load Temperature (10 sec, for soldering)	300°C	Package Thermal Resistance	
Operating Ambient Temperature		P Package (14-Pin Plastic DIP) R _{θJA}	80°C/W
C Version	0° to +70°C	WM Package (16-Pin Wide SOIC) R _{θJA}	120°C/W
B Version	–40° to +85°C	J Package (14-Pin CerDIP) R _{θJA}	100°C/W
A Version	–55° to +125°C	L Package (20-Pin LCC) R _{θJA}	120°C/W

Electrical Characteristics: Measured at T_A = 25°C with 4.5V ≤ V_S ≤ 18V unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Units
INPUT						
V _{IH}	Logic 1 Input Voltage		2.4	1.3		V
V _{IL}	Logic 0 Input Voltage			1.2	0.8	V
I _{IN}	Input Current	0 ≤ V _{IN} ≤ V _S	–1		1	μA
OUTPUT						
V _{OH}	High Output Voltage	I _{LOAD} = 10mA	V _S –0.15			V
V _{OL}	Low Output Voltage	I _{LOAD} = 10mA			0.15	V
R _O	Output Resistance	I _{OUT} = 10mA, V _S = 18V		5	15	Ω
I _{PK}	Peak Output Current			1.2		A
I	Latch-Up Protection Withstand Reverse Current		>500			mA
SWITCHING TIME						
t _R	Rise Time	Test Figure 1		14	25	ns
t _F	Fall Time	Test Figure 1		13	25	ns
t _{D1}	Delay Time	Test Figure 1		30	75	ns
t _{D2}	Delay Time	Test Figure 1		45	75	ns
POWER SUPPLY						
I _S	Power Supply Current Supply			0.2	4	mA

Electrical Characteristics:

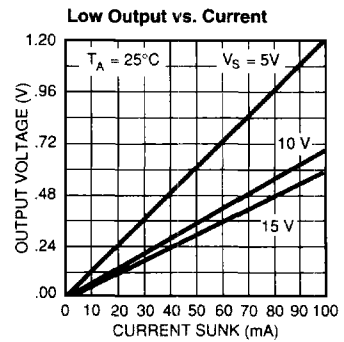
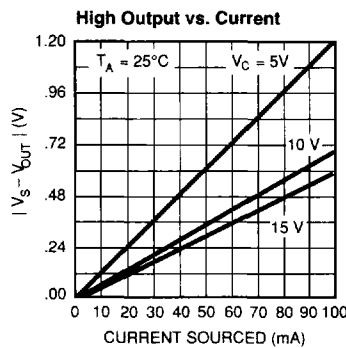
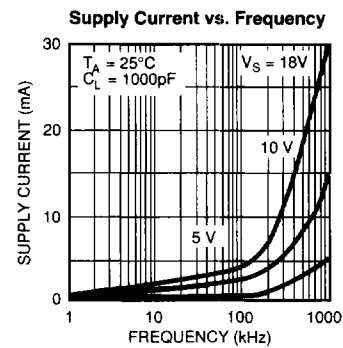
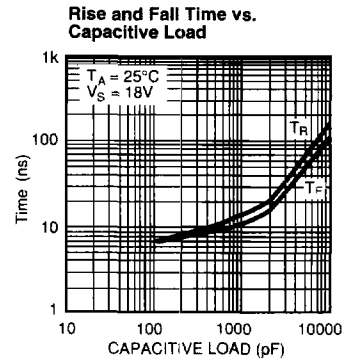
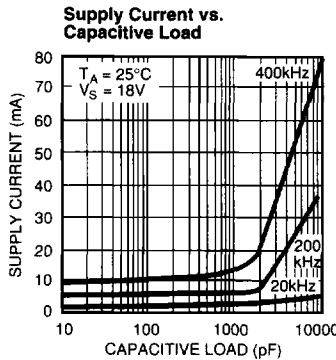
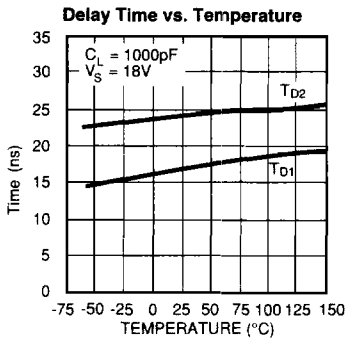
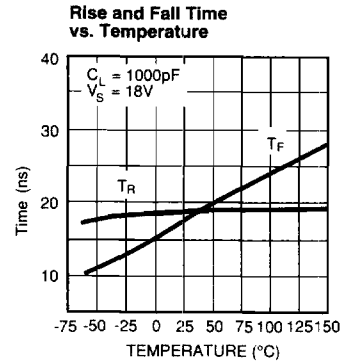
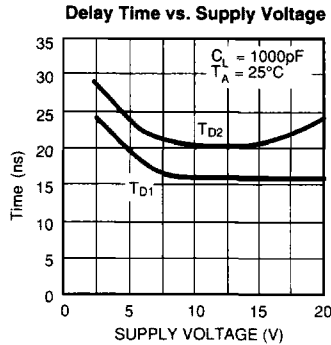
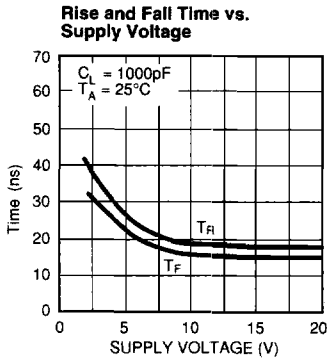
Measured over operating temperature range with $4.5V \leq V_S \leq 18V$ unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Units
INPUT						
V_{IH}	Logic 1 Input Voltage		2.4	1.4		V
V_{IL}	Logic 0 Input Voltage			1.0	0.8	V
I_{IN}	Input Current	$0 \leq V_{IN} \leq V_S$	-1		1	μA
OUTPUT						
V_{OH}	High Output Voltage	$I_{LOAD} = 10 \text{ mA}$	$V_S - 0.3$			V
V_{OL}	Low Output Voltage	$I_{LOAD} = 10 \text{ mA}$			0.3	V
R_O	Output Resistance	$I_{OUT} = 10 \text{ mA}, V_S = 18V$		7	30	Ω
I_{PK}	Peak Output Current			1.2		A
I	Latch-Up Protection Withstand Reverse Current		500			mA
SWITCHING TIME						
t_R	Rise Time	Test Figure 1		17	50	ns
t_F	Fall Time	Test Figure 1		16	50	ns
t_{D1}	Delay Time	Test Figure 1		35	100	ns
t_{D2}	Delay Time	Test Figure 1		55	100	ns
POWER SUPPLY						
I_S	Power Supply Current Supply			0.4	8	mA

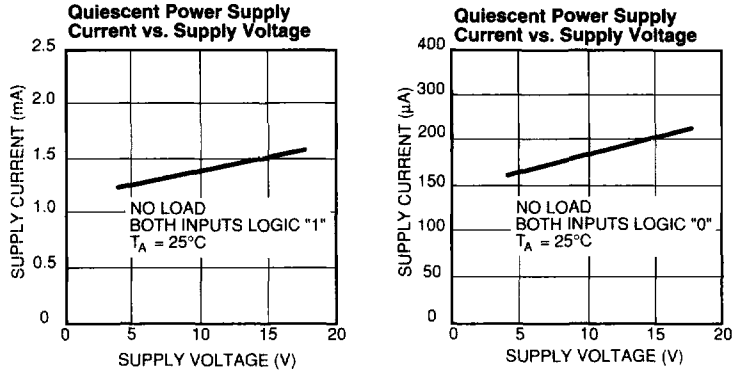
NOTE 1: Functional operation above the absolute maximum stress ratings is not implied.

NOTE 2: Static sensitive device. Store only in conductive containers. Handling personnel and equipment should be grounded to prevent static damage.

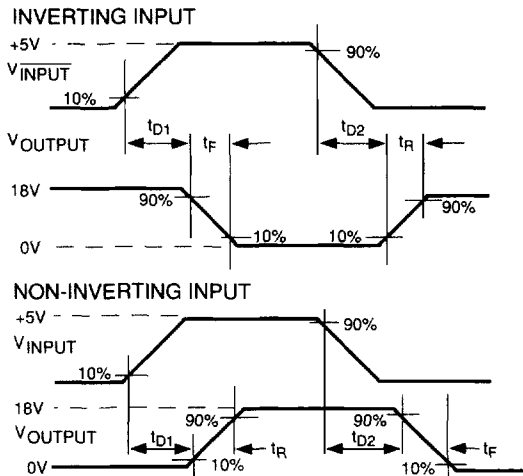
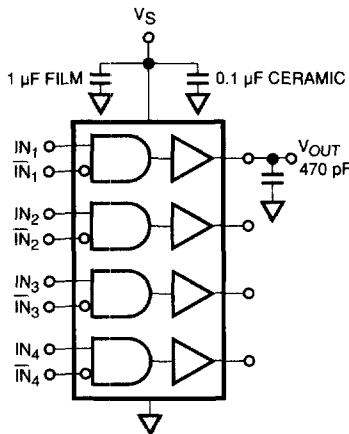
Typical Characteristics



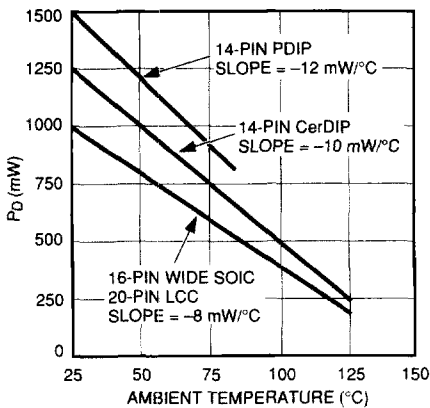
5



Test Figure 1



Package Power Dissipation



Quad Driver Drives H Bridge to Control Motor Speed and Direction

